Electronic Version
Stylesheet Version v1.1.1

SNAP-IN HEAT SINK FOR SEMICONDUCTOR MOUNTING

Abstract

A snap-in heat sink assembly that has an injection molded one piece frame having a plurality of spring members extending outwardly with protrusions at the free ends thereof. The assembly has a spring located against the frame and an electronic component is located atop of the spring. A heat sink has lateral surfaces with elongated grooves formed along those lateral surfaces. The sink is affixed to the frame by a simple step of inserting the heat sink into the space between the spring members such that the protrusions of the spring members snap into the grooves when the heat sink is in the desired location. By sandwiching the spring between the frame and the electronic component, the spring creates a bias to force the electronic component against the heat sink to assure good conductivity of heat from the electronic component through the heat sink.